



Docket No.: M4065.0248/P248-C
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Allen McTeer

Application No.: 10/656,182

Confirmation No.: 8422

Filed: September 8, 2003

Art Unit: 2815

For: A MULTI-LAYERED COPPER BOND PAD
FOR AN INTEGRATED CIRCUIT

Examiner: E. Lee

AMENDMENT AFTER FINAL ACTION (37 C.F.R. § 1.116)

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated November 29, 2005, finally rejecting claims 74-80, 82 and 83, please amend the above-identified U.S. patent application as follows:

Amendments to the Drawings begin on page 2 of this paper and included an attached replacement sheet.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks/Arguments begin on page 6 of this paper.